Electronic Patent	t App	lication Fee	Transm	ittal			
Application Number:	105	10598514					
Filing Date:	29-	29-Jan-2007					
Title of Invention:	Mu	Multiple stacked die window csp package and method of manufacture					
First Named Inventor/Applicant Name:	Chi	Chuen Khiang Wang					
Filer:	Lin	Linda Johnson Hodge/Elizabeth Whiting					
Attorney Docket Number:	P26	P26634					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filin	g Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
rost-Allowance-and-rost-issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			130